Package 封装 :BGA (Flip-Chip), Leaded (Pb)
Lead Free 无铅: No 不是

有毒有害物质名称及含量的标识格式 Table of hazardous substances' name and concentration					
均质材料 **Homogeneous Material**	铅 **Pb**	镉 **Cd**	六价铬 **Cr6+**	汞 **Hg**	多溴联苯 **PBB**
Heat Spreader 散热片	O	O	O	O	O
Substrate 基板	O	O	O	O	O
DA epoxy 贴胶	O	O	O	O	O
Die，晶片	O	O	O	O	O
Solder ball 焊球	X	O	O	O	O
Stiffener Adhesive 补强件接着剂	O	O	O	O	O
Underfill 填充料	O	O	O	O	O
FC bump pad 反晶焊点接面	X*	O	O	O	O
Solder bump 焊点	X*	O	O	O	O

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O: Indicates that the concentration of the hazardous substance in all homogeneous materials in the parts is below the relevant threshold of the SJ/T11363-2006 standard.
O: 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下.
X: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard.
X: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求.
X*: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard, but it is exempted by EU ROHS.
X*: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求。但是可以被欧盟(EU ROHS)所豁免的。

Document Revision History	
Date and Document Version	Changes Made
March 2007 v1.1	Updated table to include the symbol explanation
March 2007 v1.0	Initial Release